

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

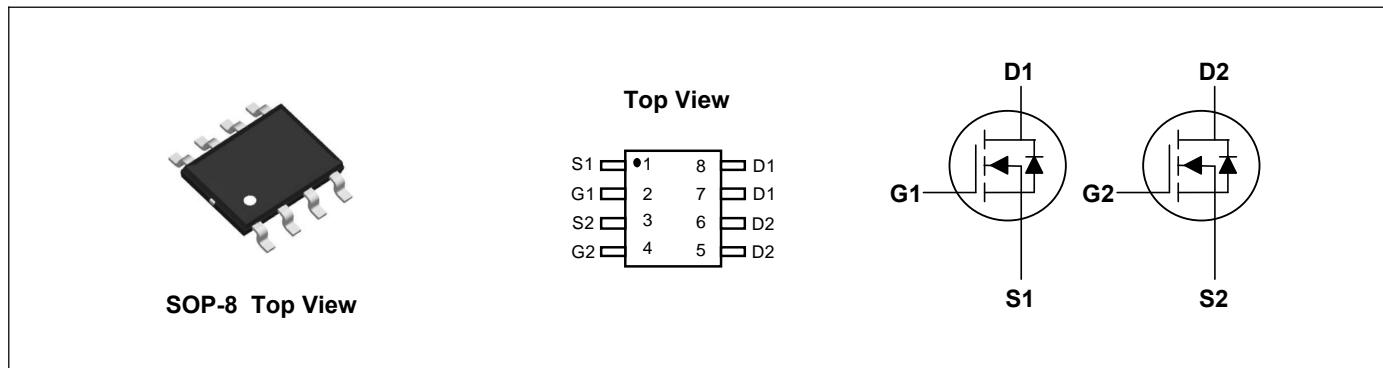
Product Summary



V_{DS}	30	V
I_D	8	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	12	mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	16	mΩ

Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



Absolute Maximum Ratings($T_A=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	8	A
Continuous Drain Current ¹	I_D	6.4	A
Pulsed Drain Current ²	I_{DM}	20	A
Single Pulse Avalanche Energy ³	EAS	16	mJ
Avalanche Current	I_{AS}	18	A
Total Power Dissipation ⁴	P_D	1.3	W
Total Power Dissipation ⁴	P_D	0.8	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	100	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
Static Drain-Source On-Resistance ²	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$	---	10	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=5\text{A}$	---	12	16	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.1	1.6	2.1	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}$, $I_D=5\text{A}$	---	2.5	---	S
Gate Resistance	R_g	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	3.2	---	Ω
Total Gate Charge	Q_g	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$	---	20.6	---	nC
Gate-Source Charge	Q_{gs}		---	2.3	---	
Gate-Drain Charge	Q_{gd}		---	4.9	---	
Turn-On Delay Time	$T_{\text{d(on)}}$	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=6\Omega$, $I_D=1\text{A}$	---	18	---	ns
Rise Time	T_r		---	31	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	31	---	
Fall Time	T_f		---	17	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	873	---	pF
Output Capacitance	C_{oss}		---	113	---	
Reverse Transfer Capacitance	C_{rss}		---	105	---	

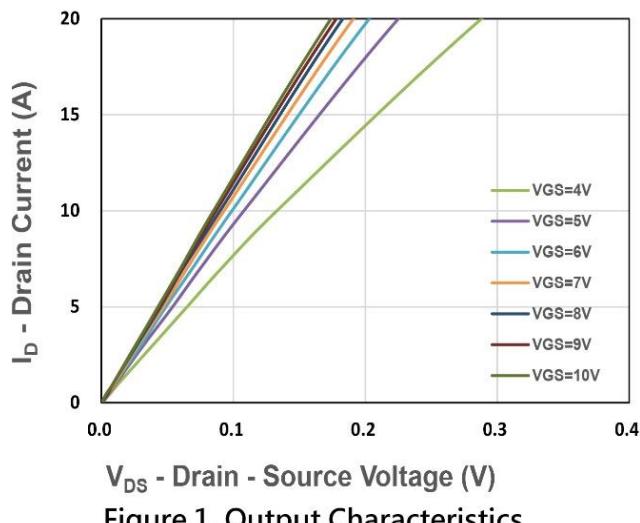
Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage ²	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	0.7	1.1	V
Reverse Recovery Time	t_{rr}	$I_F=1\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	25.5	---	nS
			---	10.8	---	nC

Note:

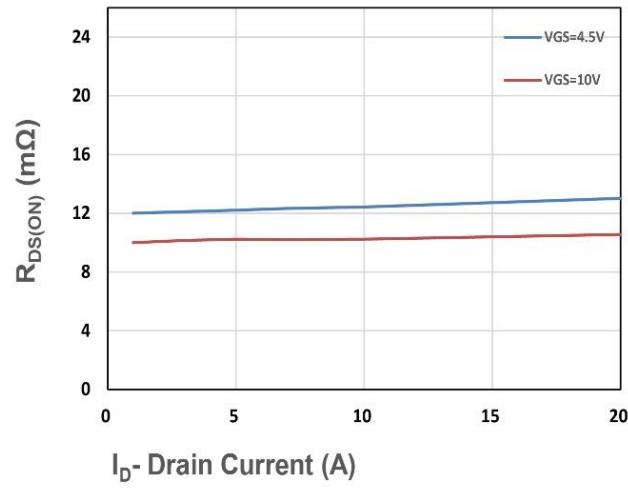
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$
- 4.The power dissipation is limited by 150°C junction temperature

Typical Characteristics



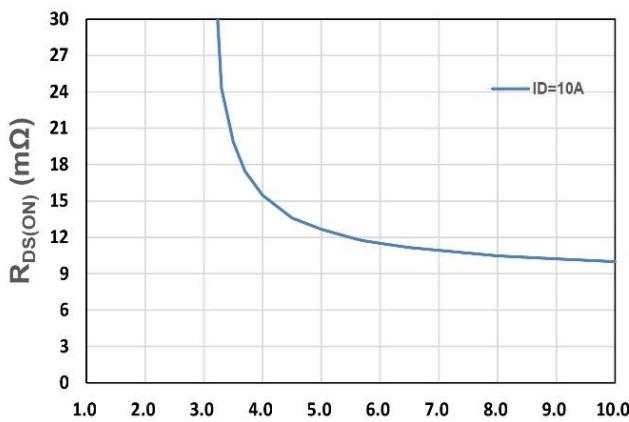
V_{DS} - Drain - Source Voltage (V)

Figure 1. Output Characteristics



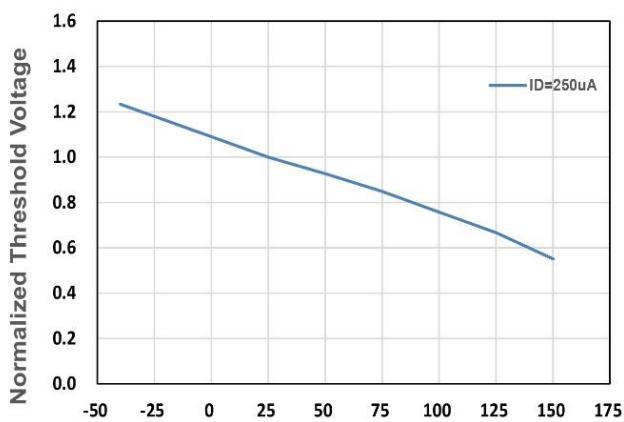
I_D - Drain Current (A)

Figure 2. On-Resistance vs. ID



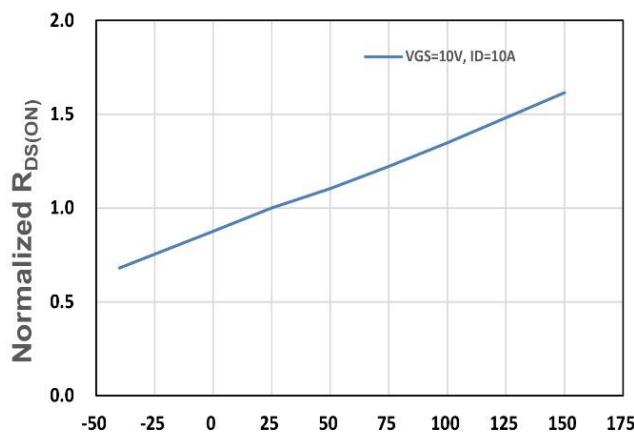
V_{GS} - Gate - Source Voltage (V)

Figure 3. On-Resistance vs. VGS



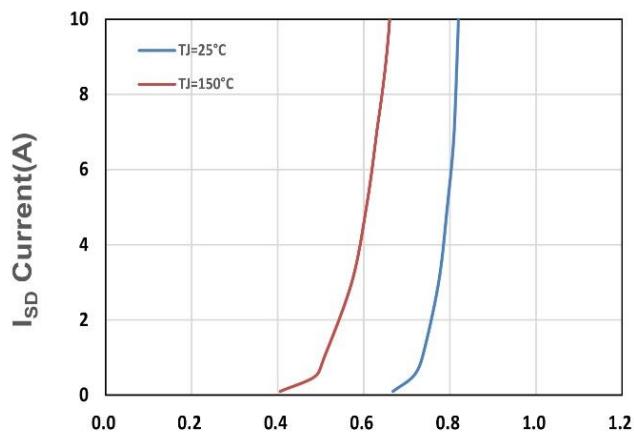
T_j , Junction Temperature(°C)

Figure 4. Gate Threshold Voltage



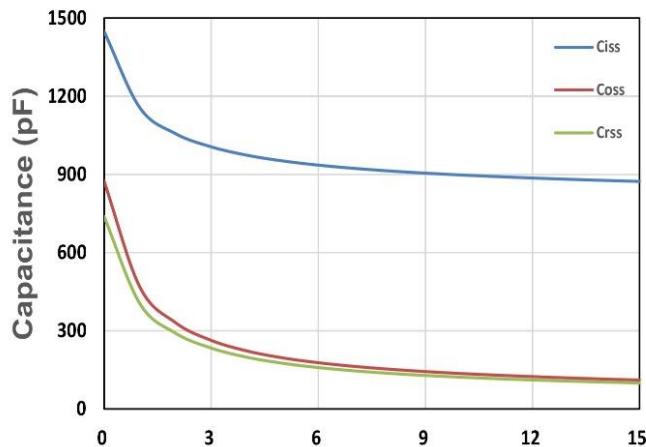
T_j , Junction Temperature(°C)

Figure 5. Drain-Source On Resistance

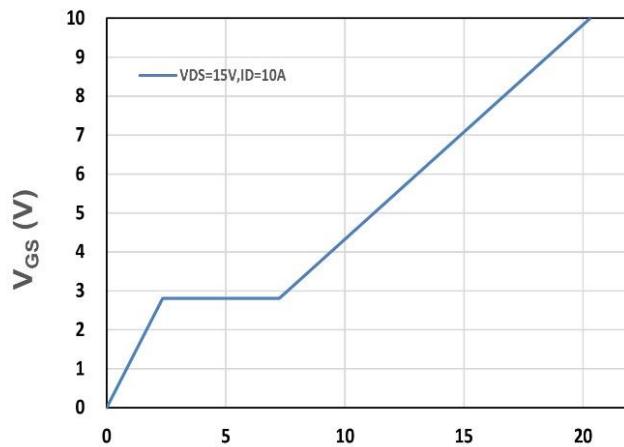


V_{SD} , Source-Drain Voltage(V)

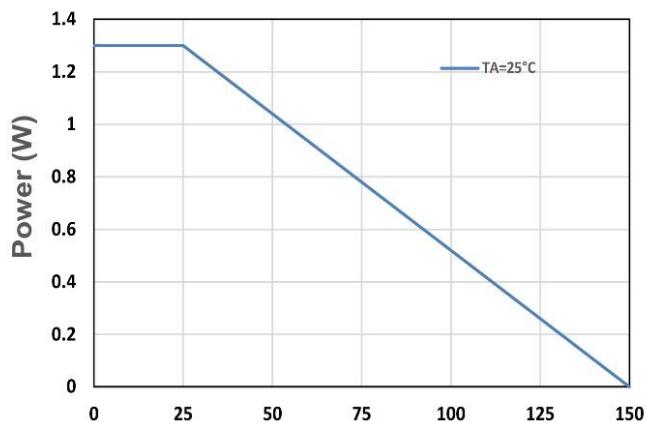
Figure 6. Source-Drain Diode Forward



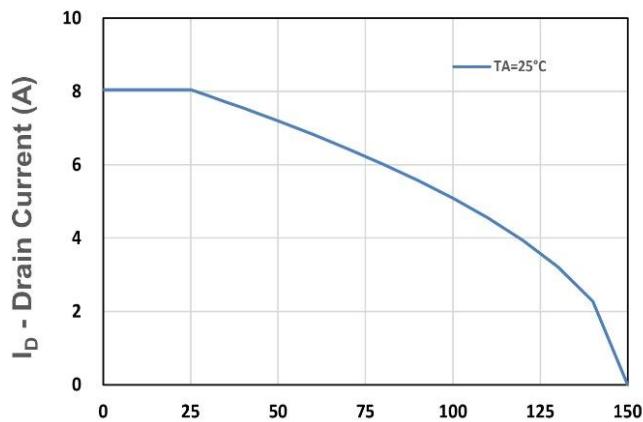
V_{DS} - Drain - Source Voltage (V)
Figure 7. Capacitance



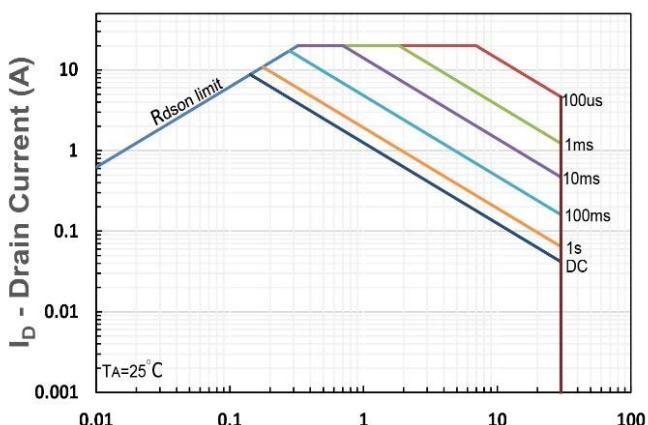
Q_g , Total Gate Charge (nC)
Figure 8. Gate Charge Characteristics



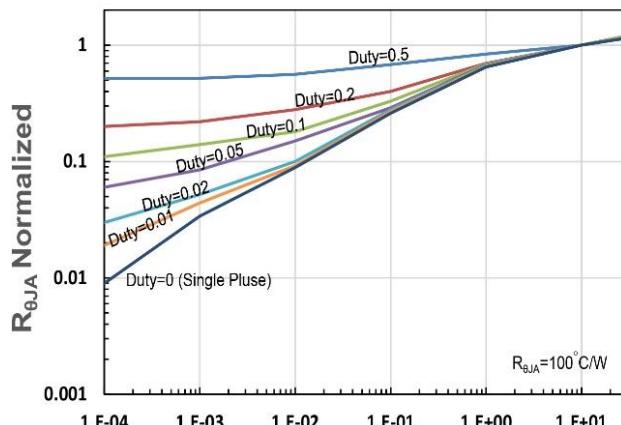
T_j - Junction Temperature (°C)
Figure 9. Power Dissipation



T_j - Junction Temperature (°C)
Figure 10. Drain Current

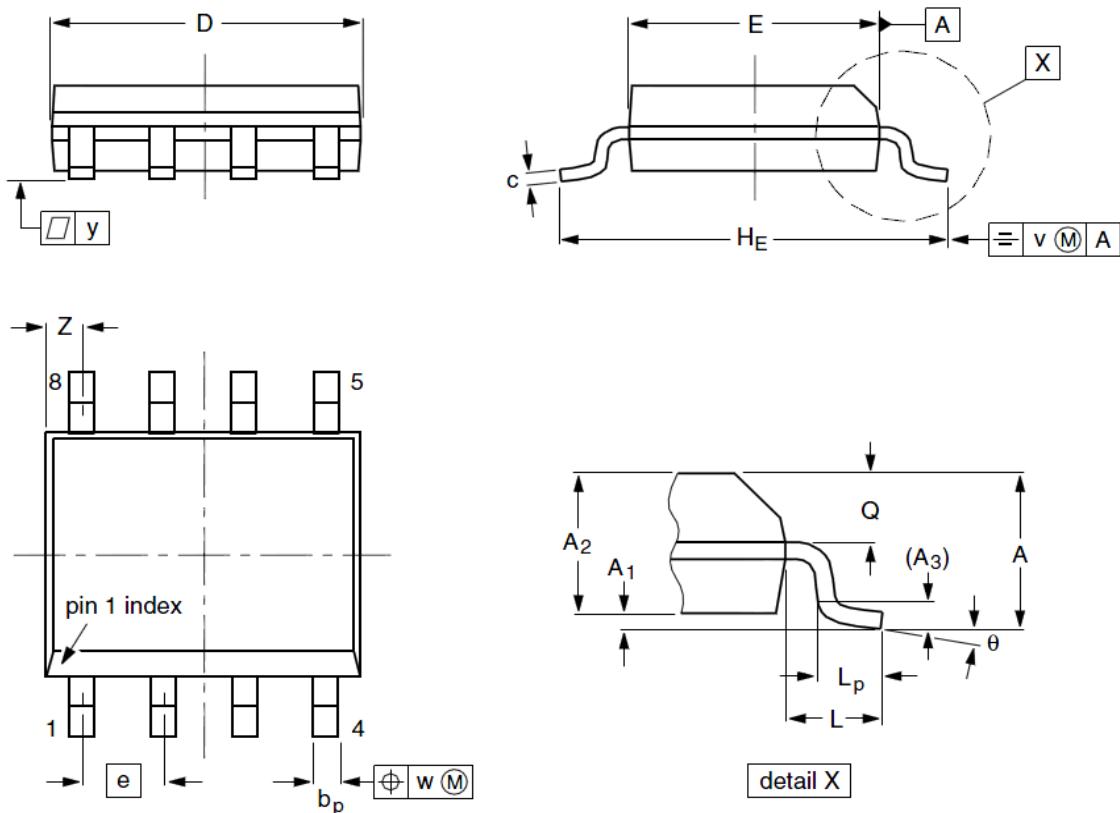


V_{DS} - Drain-Source Voltage (V)
Figure 11. Safe Operating Area



t_1 , Square Wave Pulse Duration(s)
Figure 12. $R_{\theta JA}$ Transient Thermal Impedance

SOP-8 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	1.35	1.55	1.75	A₁	0.10	0.18	0.25
A₂	1.25	1.45	1.65	A₃	--	0.25	--
b_p	0.36	0.42	0.51	c	0.19	0.22	0.25
D	4.70	4.92	5.10	E	3.80	3.90	4.00
e	--	1.27	--	H_E	5.80	6.00	6.20
L	--	1.05	--	L_P	0.40	0.68	1.00
Q	0.60	0.65	0.73	v	--	0.25	--
w	--	0.25	--	y	--	0.10	--
Z	0.30	0.50	0.70	θ	0°		8°